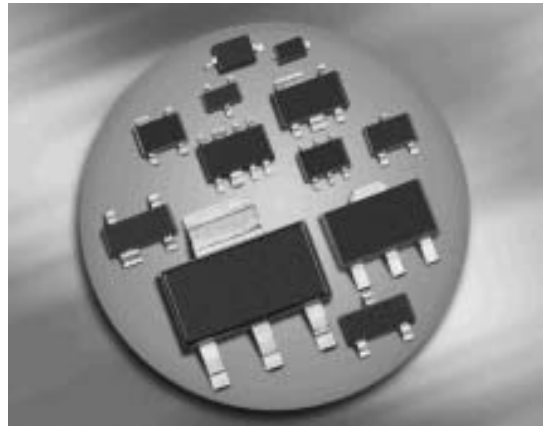
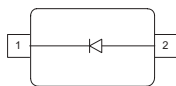


**Silicon RF Switching Diode**

- For band switching in TV/VTR tuners and mobile applications
- Very low forward resistance (typ. 0.45  $\Omega$  @ 3 mA)
- Small capacitance
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



**BA592**  
**BA892/-02L**  
**BA892-02V**



Type	Package	Configuration	$L_S$ (nH)	Marking
BA592	SOD323	single	1.8	blue S
BA892	SCD80	single	0.6	AA
BA892-02L	TSLP-2-1	single, leadless	0.4	AA
BA892-02V	SC79	single	0.6	A

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	35	V
Forward current	$I_F$	100	mA
Junction temperature	$T_j$	150	°C
Operating temperature range	$T_{op}$	-55 ... 125	
Storage temperature	$T_{stg}$	-55 ... 150	

<sup>1</sup>Pb-containing package may be available upon special request

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$		K/W
BA592		≤ 135	
BA892, BA892-02V		≤ 120	
BA892-02L		≤ 70	

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

**DC Characteristics**

Reverse current $V_R = 20\text{ V}$	$I_R$	-	-	20	nA
Forward voltage $I_F = 100\text{ mA}$	$V_F$	-	-	1	V

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

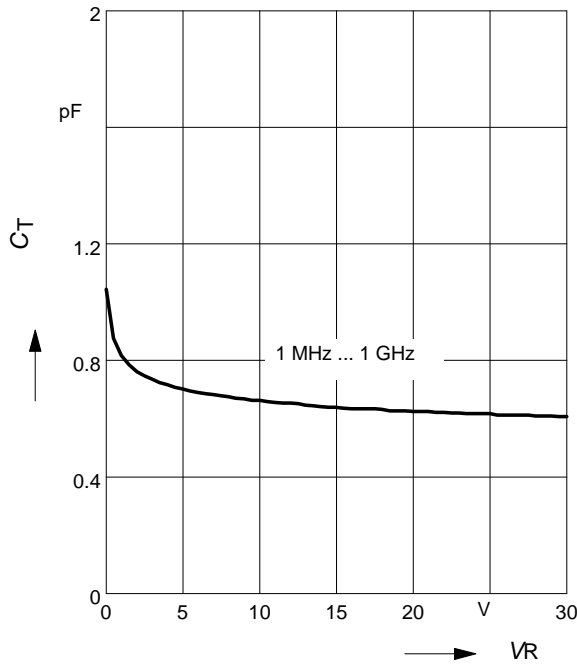
**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics</b>					
Diode capacitance $V_R = 1\text{ V}, f = 1\text{ MHz}$ $V_R = 3\text{ V}, f = 1\text{ MHz}$ $V_R = 0\text{ V}, f = 100\text{ MHz}$	$C_T$	0.65 0.6 -	0.92 0.85 1	1.4 1.1 -	pF
Reverse parallel resistance $V_R = 0\text{ V}, f = 100\text{ MHz}$	$R_P$	-	100	-	k $\Omega$
Forward resistance $I_F = 3\text{ mA}, f = 100\text{ MHz}$ $I_F = 10\text{ mA}, f = 100\text{ MHz}$	$r_f$	- -	0.45 0.36	0.7 0.5	$\Omega$
Charge carrier life time $I_F = 10\text{ mA}, I_R = 6\text{ mA}$ , measured at $I_R = 3\text{ mA}$ , $R_L = 100\ \Omega$	$\tau_{rr}$	-	120	-	ns
I-region width	$W_I$	-	3	-	$\mu\text{m}$
Insertion loss <sup>1)</sup> $I_F = 0.1\text{ mA}, f = 1.8\text{ GHz}$ $I_F = 3\text{ mA}, f = 1.8\text{ GHz}$ $I_F = 10\text{ mA}, f = 1.8\text{ GHz}$	$l_L$	- - -	0.1 0.5 0.4	- - -	dB
Isolation <sup>1)</sup> $V_R = 0\text{ V}, f = 100\text{ MHz}$ $V_R = 0\text{ V}, f = 470\text{ MHz}$ $V_R = 0\text{ V}, f = 1\text{ GHz}$	$l_{SO}$	- - -	23.5 10.5 5.5	- - -	

<sup>1</sup>BA892-02L in series configuration,  $Z = 50\ \Omega$

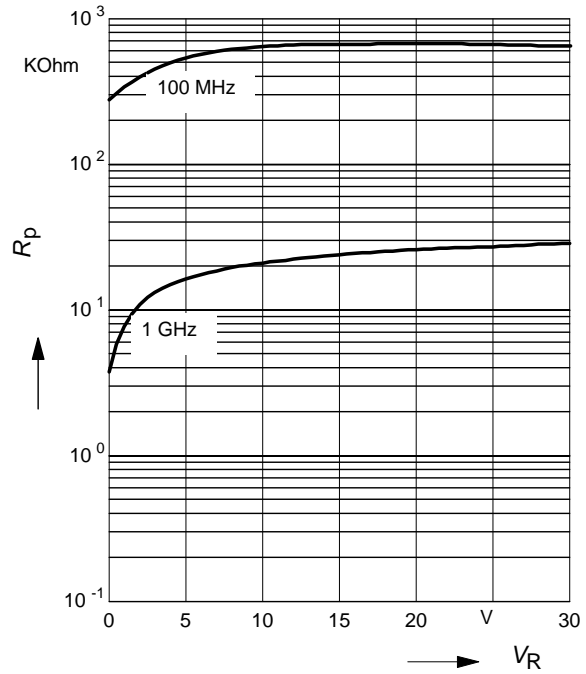
**Diode capacitance  $C_T = f(V_R)$**

$f = \text{Parameter}$



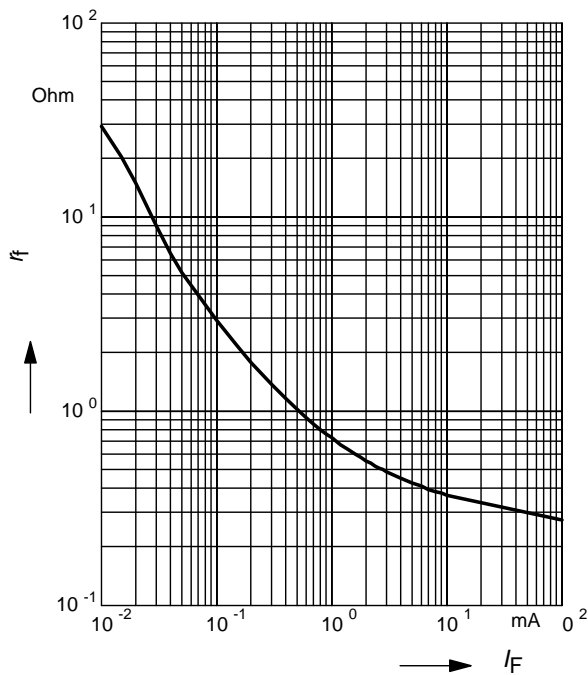
**Reverse parallel resistance  $R_p = f(V_R)$**

$f = \text{Parameter}$



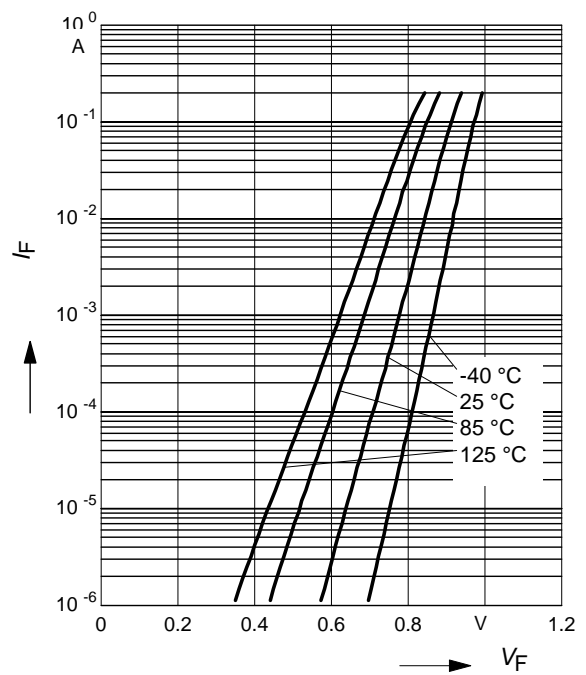
**Forward resistance  $r_f = f(I_F)$**

$f = 100\text{MHz}$



**Forward current  $I_F = f(V_F)$**

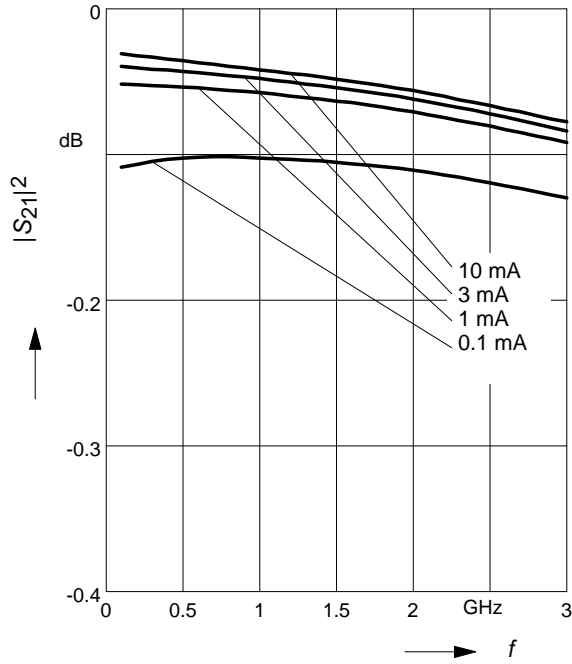
$T_A = \text{Parameter}$



**Insertion loss**  $I_L = -|S_{21}|^2 = f(f)$

$I_F =$  Parameter

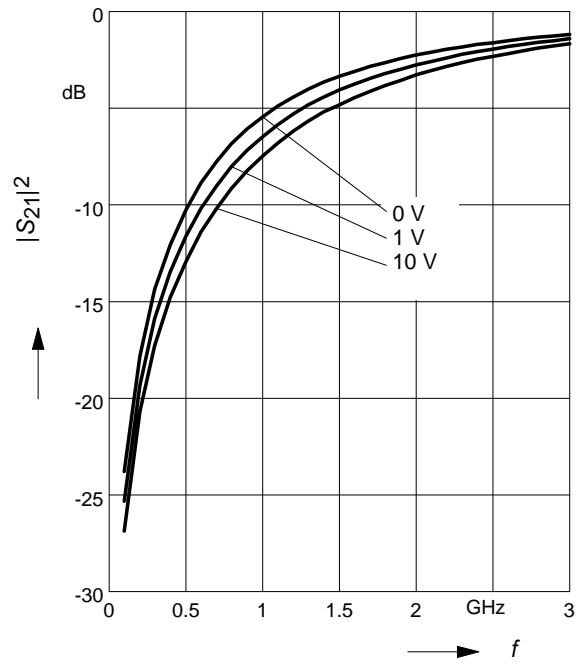
BA892-02L in series configuration,  $Z = 50\Omega$



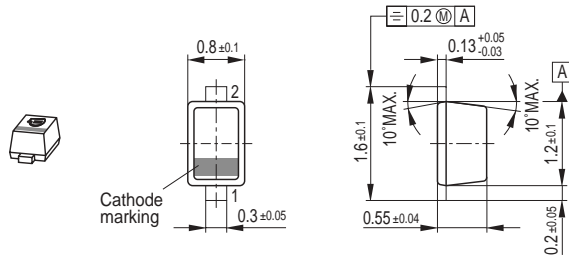
**Isolation**  $I_{SO} = -|S_{21}|^2 = f(f)$

$V_R =$  Parameter

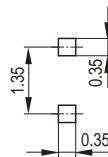
BA892-02L in series configuration,  $Z = 50\Omega$



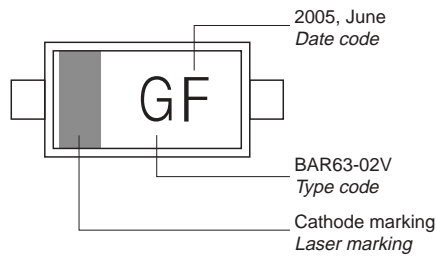
Package Outline



Foot Print

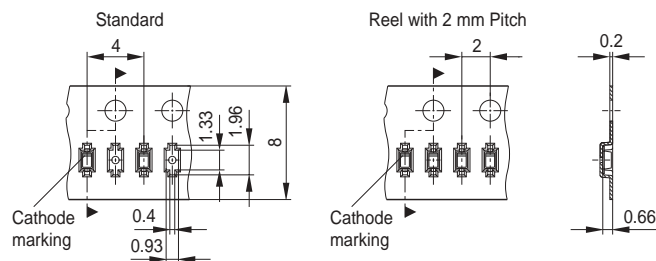


Marking Layout (Example)

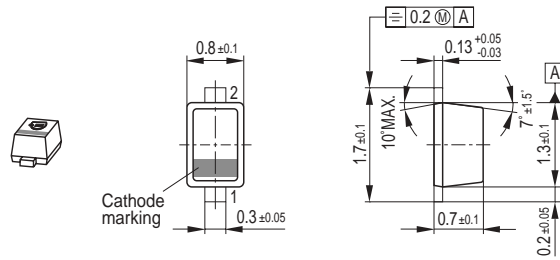


Standard Packing

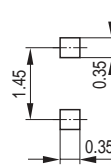
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 180 mm = 8.000 Pieces/Reel (2 mm Pitch)  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



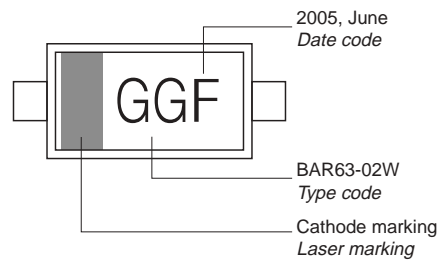
Package Outline



Foot Print

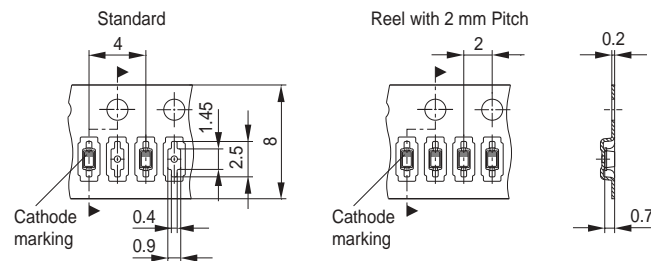


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 180 mm = 8.000 Pieces/Reel (2 mm Pitch)  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



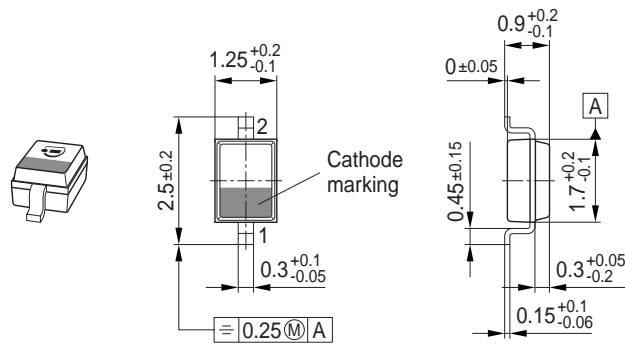
Date Code marking for discrete packages with  
one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

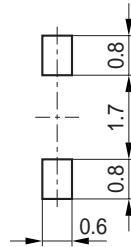
1) New Marking Layout for SC75, implemented at October 2005.



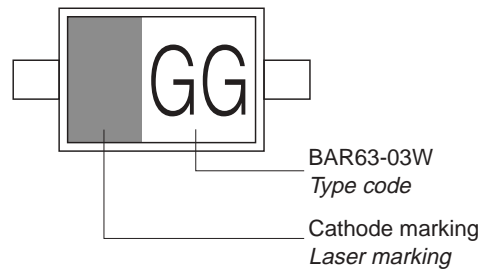
Package Outline



Foot Print

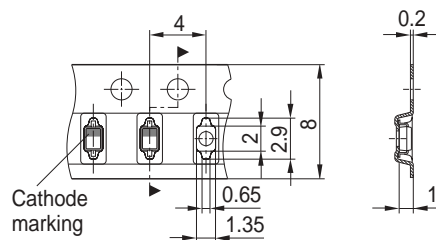


Marking Layout (Example)

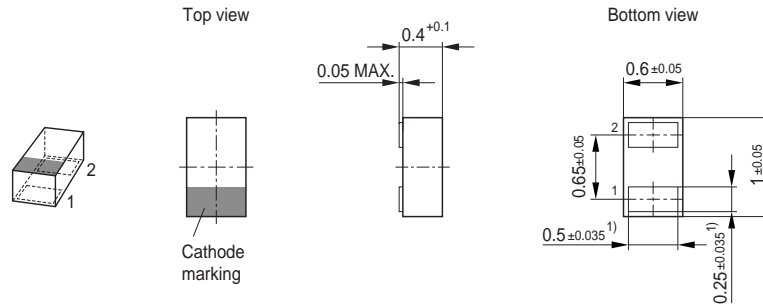


Standard Packing

Reel  $\varnothing 180$  mm = 3.000 Pieces/Reel  
 Reel  $\varnothing 330$  mm = 10.000 Pieces/Reel



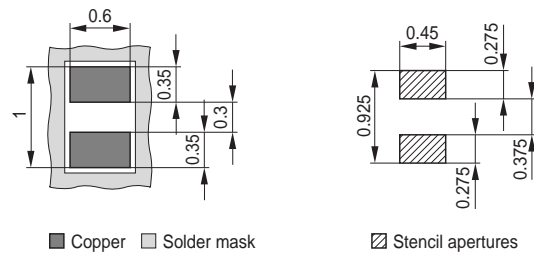
### Package Outline



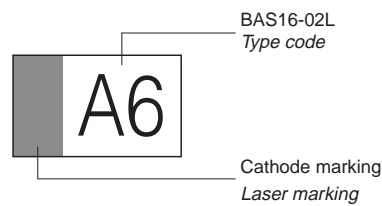
1) Dimension applies to plated terminal

### Foot Print

For board assembly information please refer to Infineon website "Packages"

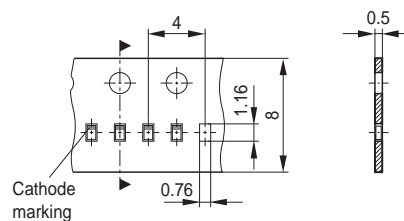


### Marking Layout (Example)



### Standard Packing

Reel  $\varnothing$ 180 mm = 15.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 50.000 Pieces/Reel (optional)



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